

# Automotive Cluster Telltale Driver Reference Design - TIDA-00278



Available

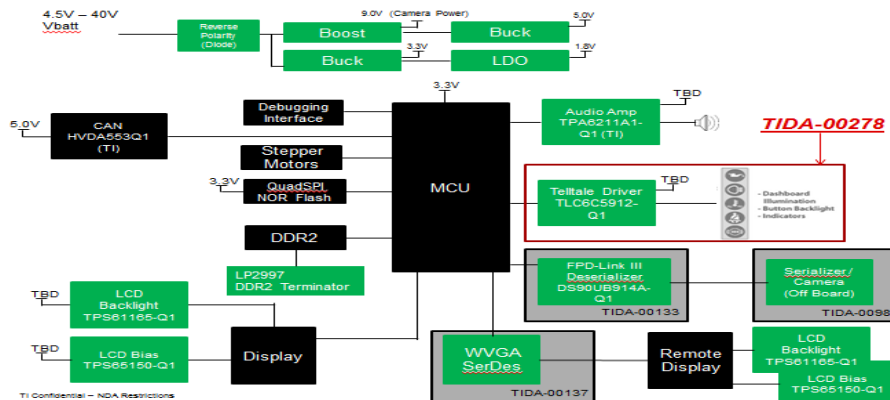
## Solution Features

- Low and accurate R<sub>dson</sub> for the internal MOSFET
- Slow switching time: rise time=207ns fall time=128ns
- Thermal shutdown protection
- The entire cluster solution supports 4.5V-40V system capabilities

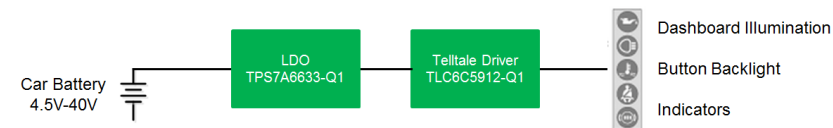
## Solution Benefits

- Allowing low thermal dissipation and more accurate output current passing through the LED.
- Significantly helps in reducing EMI
- Helping avoid overheating and damaging the TLC6C5912-Q1 IC.
- Overall cluster system can withstand start/stop, cold crank, and load dump conditions.

## Tools & Resources



## TIDA-00278



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